

Description

The 8331 Silver Conductive Epoxy Adhesive is an electric grade epoxy with high electrical and thermal conductivities, and it bonds very well to a variety of surfaces. It is easy to use and has a convenient 1 to 1 ratio. It does not require high temperatures to cure, curing minutes at 65C or a few hours at room temperature.

Applications & Usages

The 8331 epoxy has many uses. It is primarily used as a solder replacement for bonding heat-sensitive electronic components. It allows for quick cold soldering repairs, and is effective at bonding heat sinks to other components and PCBs. It also provides excellent EMI/RFI shielding, and is very effective at filling in seems between metal plates.

Its primary applications are repair and assembly of electronics in microelectronics and optoelectronics. It is used in the automobile, aerospace, marine communication, instrumentation, and industrial control equipment industries.

Benefits

- Excellent electrical and thermal conductivity
- Easy 1:1 mix ratio

Curing & Work Schedule^a

- Strong water and chemical resistance to brine, acids, bases, and aliphatic hydrocarbons
- Provides excellent EMI/RFI Shielding

Properties	Value
Working Life	10 min
Shelf Life	≥3 year
Full Cure (at 25 °C [77 °F])	5 hour
Full Cure (at 65 °C [149 °F])	15 min
Full Cure (at 90 °C [194 °F])	12 min
Full Cure (at 125 °C [257 °F])	7 min
Full Cure (at 150 °C [302 °F])	5 min
Storage Temperature	16 to 27 °C
of Unmixed Parts	[60 to 80 °F]

a) Cure and life values 5 g and room

temperature unless stated otherwise.

Temperature Service Range

Properties	Value
Constant Service Temp.	-40 °C to 150 °C [-40 to 302 °F]



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Principal Components

Name

Part A: Bis-F Epoxide Resin Metallic Silver Part B: Aliphatic Amines Metallic Silver

CAS Number

28064-*14-4* 7440-22-4 *140-31-8* + *84852-15-3* + *68411-71-2* + *111-40-0* 7440-22-4

Properties of Cured 8331

Physical Properties	Method	Value ^a
Color	Visual	Silver Grey
Density (at 26 °C)		2.44 g/cm ³
Hardness	(Shore D durometer)	70D to 75D
Tensile Strength	ASTM D 638	6.28 N/mm ² [911 lb/in ²]
Elongation	"	0.30%
Shear Strength	ASTM D 732	1.61 N/mm ² [234 lb/in ²]
Izod Impact ^b	ASTM D 256	1.7 kJ/m ² [0.80 ft·lb/in]
Compression Strength	ASTM D 695	7.56 N/mm ² [1,090 lb/in ²]
Flexural Strength	ASTM D 790	17.2 N/mm ² [2,500 lb/in ²]
Outgassing (Total Mass Loss) @ 24 h	ASTM E 595	7.16%
@ 48 h		6.11%
Solderable		No
Electric Properties	Method	Value
<i>Electric Properties</i> Volume Resistivity ^c	Method MIL-STD-883E	<i>Value</i> 0.18 Ω·cm
Volume Resistivity ^c		0.18 Ω·cm
Volume Resistivity ^c Dielectric Dissipation & Constant	MIL-STD-883E	$0.18 \ \Omega \cdot cm$ dissipation, D constant, k'
Volume Resistivity ^c Dielectric Dissipation & Constant	MIL-STD-883E	$0.18 \ \Omega \cdot cm$ dissipation, D constant, k'
Volume Resistivity ^c Dielectric Dissipation & Constant @1 MHz	MIL-STD-883E ASTM D 150-98	0.18 Ω·cm <i>dissipation, D</i> constant, k' 0.012 3.01
Volume Resistivity ^c Dielectric Dissipation & Constant @1 MHz Thermal Properties	MIL-STD-883E ASTM D 150-98 <i>Method</i>	0.18 Ω·cm dissipation, D constant, k' 0.012 3.01 Value
Volume Resistivity ^c Dielectric Dissipation & Constant @1 MHz <u>Thermal Properties</u> Thermal Conductivity @25 °C	MIL-STD-883E ASTM D 150-98 <u>Method</u> ASTM E 1461	0.18 Ω·cm <i>dissipation, D</i> constant, k' 0.012 3.01 <i>Value</i> 0.903 W/(m·K) 0.893 W/(m·K) 0.813 W/(m·K)
Volume Resistivity ^c Dielectric Dissipation & Constant @1 MHz Thermal Properties Thermal Conductivity @25 °C @50 °C @100 °C Glass Transition Temperature (T _q)	MIL-STD-883E ASTM D 150-98 Method ASTM E 1461	0.18 Ω·cm <i>dissipation, D</i> constant, k' 0.012 3.01 Value 0.903 W/(m·K) 0.893 W/(m·K) 0.813 W/(m·K) 55.1 °C [131 °F]
Volume Resistivity ^c Dielectric Dissipation & Constant @1 MHz Thermal Properties Thermal Conductivity @25 °C @50 °C @100 °C Glass Transition Temperature (T _q) CTE ^d prior T _q	MIL-STD-883E ASTM D 150-98 Method ASTM E 1461 " ASTM D 3418 ASTM E 831	0.18 Ω·cm <i>dissipation, D</i> constant, k' 0.012 3.01 <i>Value</i> 0.903 W/(m·K) 0.893 W/(m·K) 0.813 W/(m·K) 55.1 °C [131 °F] 38.5 ppm/°C
Volume Resistivity ^c Dielectric Dissipation & Constant @1 MHz Thermal Properties Thermal Conductivity @25 °C @50 °C @100 °C Glass Transition Temperature (T _q)	MIL-STD-883E ASTM D 150-98 Method ASTM E 1461 " ASTM D 3418	0.18 Ω·cm <i>dissipation, D</i> constant, k' 0.012 3.01 Value 0.903 W/(m·K) 0.893 W/(m·K) 0.813 W/(m·K) 55.1 °C [131 °F]

Note: Specifications are for epoxy samples that were cured at 65 °C for 1 hour. Additional curing time at room temperature was given to allow for optimum curing. Samples were conditioned at 23 °C and 50% RH prior to most tests.

a) N/mm² = mPa; Ib/in^2 = psi

b) Cantilever beam impact

c) The uncured epoxy mixture does not conduct electricity well and can have high resistance. To attain stated resistivity, ensure that the mix ratio is followed and that the product is fully cured by heat curing. Room temperature cures may give higher resistivity of about 0.8 Ω /sq.

d) Coefficient of Thermal Expansion (CTE) units are in ppm/°C = in/in/°C $\times 10^{-6}$ = unit/unit/°C $\times 10^{-6}$



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Properties of Uncured 8331

Physical Property	Mixture (1A:1B)			
Color	Silver Grey			
Density	2.34 g/mL			
Mix Ratio by volume (A:B)	1:0:1.0			
Mix Ratio by weight (A:B)	1.2:1.0			
Solids Content (w/w)	93%			
Physical Property	Part A	Part B		
Color	Silver Grey	Silver Grey		
Density	2.47 g/mL	2.20 g/mL		
Flash Point	N/E	>93 °C [199 °F]		
Resistivity of uncured material	Off-scale (no reading)	Off-scale (no reading)		

Compatibility

Adhesion—As seen in the substrate adhesion table, the 8331 epoxy adheres to most materials found on printed circuit assemblies; however, it is not compatible with contaminants like water, oil, and greasy flux residues that may affect adhesion. If contamination is present, clean the printed circuit assembly with electronic cleaner such as MG Chemicals 4050 Safety Wash, 406B Superwash, or 824 Isopropyl Alcohol.

Substrate Adhesion in Decreasing Order

Physical Properties	Adhesion	
Aluminum	Stronger	
Steel		
Fiberglass		
Wood		
Paper, Fiber		
Glass		
Rubber		
Polycarbonate		
Acrylic	•	
Polypropylene ^a	Weaker	

a) Does not bond to polypropylene



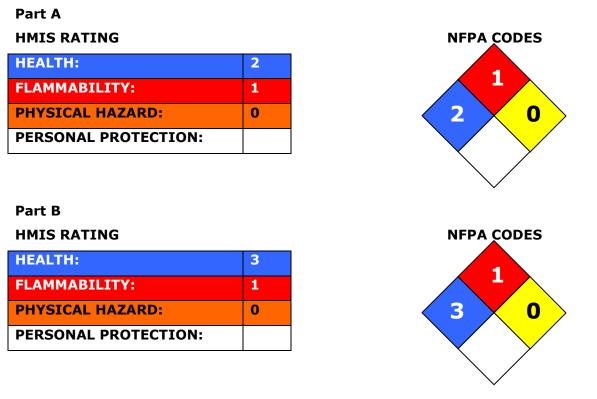
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Storage

Store between 16 and 27 °C [60 and 80 °F] in dry area away from sunlight. Prolonged storage or storage at or near freezing temperatures can result in crystallization. If crystallization occurs, reconstitute the component to its original state by temporarily warming it to 50 to 60 °C [122 to 140 °F]. To ensure full homogeneity, stir thoroughly the warm component, reincorporating all settled material. Re-secure container lid and let cool down before use.

Health and Safety

Please see the 8331 **Material Safety Data Sheet** (MSDS) parts A and B for more details on transportation, storage, handling and other security guidelines.



Health and Safety: The 8331 parts can ignite if the liquid is both heated and exposed to flames or sparks.

Wear safety glasses or goggles and disposable polyvinyl chloride, neoprene, or nitrile gloves while handling liquids. Part B in particular causes skin burns and may cause sensitization if exposed over a long period of time. The epoxy will not wash off once cured: wear protective work clothing. Wash hands thoroughly after use or if skin contact occurs. Do not ingest.

Use in well-ventilated area since vapors may cause irritation of the respiratory tract and cause respiratory sensitization in susceptible individuals.

The cured epoxy resin presents no known hazard.



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Application Instructions

Follow the procedure below for best results.

To prepare 1:1 (A:B) epoxy mixture

- 1. Remove cap or cover.
- 2. Measure **one** parts by volume **A**.
- 3. Measure **one** part by volume of **B**.
- 4. Thoroughly mix the parts together with a stir stick until homogeneous.
- 5. Apply to with an appropriate sized stick for the application area.

NOTE: Remember to recap the syringe or container promptly after use.

TIP: Due to the high viscosity and abrasiveness of the silver filler, you may preheat parts A and part B to increase the flow and improve air release.

To room temperature cure the 8331 epoxy

Let stand for 5 hour.

To heat cure the 8331 epoxy

Put in oven at 65 °C [149 °F] for 15 minute.

You can cure the epoxy faster by using higher temperatures of up to 150 °C [302 °F].

<u>ATTENTION</u>: Keep the curing temperature well below temperature limit of heat sensitive components that may be present.

Application Notes

A slight discoloration of the 8331 epoxy may occur over time. The discoloration does not affect the adhesiveness or conductivity.

This product cannot be soldered through cleanly and safely for the printed circuit assembly components.



Packaging and Supporting Products

Product Availability

Cat. No.	Form	Net Volume		Net Weight		Shipping Weight	
8331-14G	Liquid	10 mL	0.35 oz	14 g	0.031 lb	32 g	0.07 lb
8331-454G	Liquid	336 mL	11.4 oz	454 g	1.00 lb	0.65 kg	1.4 lb

Technical Support

Contact us regarding any questions, improvement suggestions, or problems with this product. Application notes, instructions, and FAQs are located at <u>www.mgchemicals.com</u>.

Email: support@mgchemicals.com

Phone: 1-800-201-8822 Ext. 128 (Canada, Mexico & USA) 1-604-888-3084 Ext. 128 (International) Fax: 1-604-888-7754 or 1-800-708-9888

Mailing address: Manufacturing & Support 1210 Corporate Drive Burlington, Ontario, Canada L7L 5R6 Head Office 9347–193rd Street Surrey, British Columbia, Canada V4N 4E7

Warranty

M.G. Chemicals Ltd. warranties this product for 12 months from the date of purchase by the end user. M.G. Chemicals Ltd. makes no claims as to shelf life of this product for the warranty. The liability of M.G. Chemicals Ltd. whether based on its warranty, contracts, or otherwise shall in no case include incidental or consequential damage.

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